



CY54/74FCT157T

Quad 2-Input Multiplexer

Features

- Function, pinout, and drive compatible with FCT and F logic
- FCT-C speed at 4.3 ns max. (Com'l), FCT-A speed at 5.0 ns max. (Com'l)
- Reduced V_{OH} (typically = 3.3V) versions of equivalent FCT functions
- Edge-rate control circuitry for significantly improved noise characteristics
- Power-off disable feature
- Matched rise and fall times
- Fully compatible with TTL input and output logic levels
- ESD > 2000V
- Extended commercial range of -40°C to +85°C
- Sink current 64 mA (Com'l),
 32 mA (Mil)
- Source current 32 mA (Com'l),
 12 mA (Mil)

Functional Description

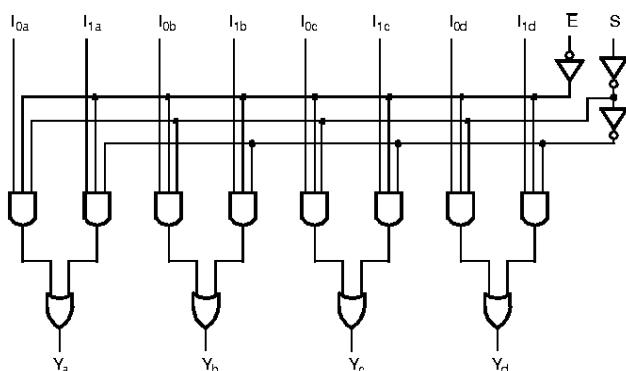
The FCT157T is a quad two-input multiplexer that select four bits of data from two sources under the control of a common data Select input (S). The Enable input (E) is Active LOW. When (E) is HIGH, all of the outputs (Y) are forced LOW regardless of all other input conditions.

Moving data from two groups of registers to four common output buses is a common use of the FCT157T. The state of the Select input determines the particular register from which the data comes. It can also be used as a function generator. The device is useful for implementing highly irregular logic by generating any four of the sixteen different functions of two variables with one variable common.

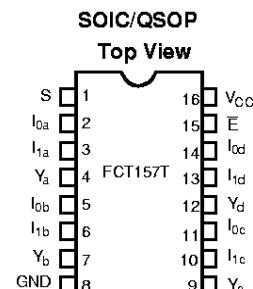
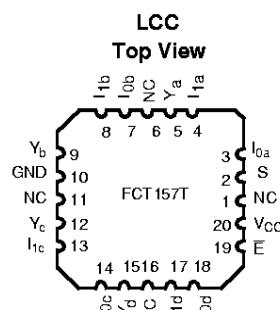
The FCT157T is a logic implementation of a four-pole, two-position switch where the position of the switch is determined by the logic levels supplied to the Select input.

The outputs are designed with a power-off disable feature to allow for live insertion of boards.

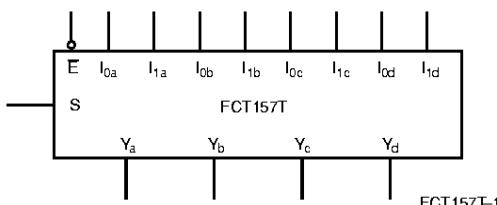
Logic Block Diagram, FCT157T



Pin Configurations



Logic Symbol



Pin Description

| Name | Description |
|----------------|----------------------------|
| S | Common Select Input |
| E | Enable Inputs (Active LOW) |
| I ₀ | Data Inputs from Source 0 |
| I ₁ | Data Inputs from Source 1 |
| Y | Non-Inverted Output |

Function Table^[1]

| Inputs | | | | Outputs |
|--------|---|----------------|----------------|---------|
| E | S | I ₀ | I ₁ | Y |
| H | X | X | X | L |
| L | H | X | L | L |
| L | H | X | H | H |
| L | L | L | X | L |
| L | L | H | X | H |

Maximum Ratings^[2,3]

(Above which the useful life may be impaired. For user guidelines, not tested.)

| | |
|--|--|
| Storage Temperature | -65°C to +150°C |
| Ambient Temperature with Power Applied..... | -65°C to +135°C |
| Supply Voltage to Ground Potential | -0.5V to +7.0V |
| DC Input Voltage | -0.5V to +7.0V |
| DC Output Voltage | -0.5V to +7.0V |
| DC Output Current (Maximum Sink Current/Pin) | 120 mA |
| Power Dissipation..... | 0.5W |
| Static Discharge Voltage | >2001V (per MIL-STD-883, Method 3015) |

Operating Range

| Range | Range | Ambient Temperature | V _{CC} |
|-------------------------|-------|---------------------|-----------------|
| Commercial | All | -40°C to +85°C | 5V ± 5% |
| Military ^[4] | All | -55°C to +125°C | 5V ± 10% |

Electrical Characteristics Over the Operating Range

| Parameter | Description | Test Conditions | Min. | Typ. ^[5] | Max. | Unit | |
|------------------|---|---|-------|---------------------|------|------|---|
| V _{OH} | Output HIGH Voltage | V _{CC} =Min., I _{OH} =-32 mA | Com'l | 2.0 | | V | |
| | | V _{CC} =Min., I _{OH} =-15 mA | Com'l | 2.4 | 3.3 | V | |
| | | V _{CC} =Min., I _{OH} =-12 mA | Mil | 2.4 | 3.3 | V | |
| V _{OL} | Output LOW Voltage | V _{CC} =Min., I _{OL} =64 mA | Com'l | | 0.3 | 0.55 | V |
| | | V _{CC} =Min., I _{OL} =32 mA | Mil | | 0.3 | 0.55 | V |
| V _{IH} | Input HIGH Voltage | | 2.0 | | | V | |
| V _{IL} | Input LOW Voltage | | | | 0.8 | V | |
| V _H | Hysteresis ^[6] | All inputs | | 0.2 | | V | |
| V _{IK} | Input Clamp Diode Voltage | V _{CC} =Min., I _{IN} =-18 mA | | -0.7 | -1.2 | V | |
| I _I | Input HIGH Current | V _{CC} =Max., V _{IN} =V _{CC} | | | 5 | µA | |
| I _{IH} | Input HIGH Current | V _{CC} =Max., V _{IN} =2.7V | | | ±1 | µA | |
| I _{IL} | Input LOW Current | V _{CC} =Max., V _{IN} =0.5V | | | ±1 | µA | |
| I _{OZH} | Off State HIGH-Level Output Current | V _{CC} = Max., V _{OUT} = 2.7V | | | 10 | µA | |
| I _{OZL} | Off State LOW-Level Output Current | V _{CC} = Max., V _{OUT} = 0.5V | | | -10 | µA | |
| I _{OS} | Output Short Circuit Current ^[7] | V _{CC} =Max., V _{OUT} =0.0V | -60 | -120 | -225 | mA | |
| I _{OFF} | Power-Off Disable | V _{CC} =0V, V _{OUT} =4.5V | | | ±1 | µA | |

Note:

1. H = HIGH Voltage Level. L = LOW Voltage Level. X = Don't Care
2. Unless otherwise noted, these limits are over the operating free-air temperature range.
3. Unused inputs must always be connected to an appropriate logic voltage level, preferably either V_{CC} or ground.
4. T_A is the "instant on" case temperature.
5. Typical values are at V_{CC}=5.0V, T_A=+25°C ambient.
6. This parameter is guaranteed but not tested.
7. Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample and hold techniques are preferable in order to minimize internal chip heating and more accurately reflect operational values. Otherwise prolonged shorting of a high output may raise the chip temperature well above normal and thereby cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

Capacitance^[6]

| Parameter | Description | Typ. ^[5] | Max. | Unit |
|-----------|--------------------|---------------------|------|------|
| C_{IN} | Input Capacitance | 5 | 10 | pF |
| C_{OUT} | Output Capacitance | 9 | 12 | pF |

Power Supply Characteristics

| Parameter | Description | Test Conditions | Typ. ^[5] | Max. | Unit |
|-----------------|--|---|---------------------|---------------------|--------|
| I_{CC} | Quiescent Power Supply Current | $V_{CC}=\text{Max.}, V_{IN}\leq 0.2V, V_{IN}\geq V_{CC}-0.2V$ | 0.1 | 0.2 | mA |
| ΔI_{CC} | Quiescent Power Supply Current (TTL inputs HIGH) | $V_{CC}=\text{Max.}, V_{IN}=3.4V$ ^[8] , $f_1=0$, Outputs Open | 0.5 | 2.0 | mA |
| I_{CCD} | Dynamic Power Supply Current ^[9] | $V_{CC}=\text{Max.}, \text{One Input Toggling, 50\% Duty Cycle, Outputs Open, } \overline{OE}=\text{GND, } V_{IN}\leq 0.2V \text{ or } V_{IN}\geq V_{CC}-0.2V$ | 0.06 | 0.12 | mA/MHz |
| I_C | Total Power Supply Current ^[10] | $V_{CC}=\text{Max.}, 50\% \text{ Duty Cycle, Outputs Open, One Input Toggling at } f_1=10 \text{ MHz, } \overline{OE}=\text{GND, } V_{IN}\leq 0.2V \text{ or } V_{IN}\geq V_{CC}-0.2V$ | 0.7 | 1.4 | mA |
| | | $V_{CC}=\text{Max.}, 50\% \text{ Duty Cycle, Outputs Open, One Input Toggling at } f_1=10 \text{ MHz, } \overline{OE}=\text{GND, } V_{IN}=3.4V \text{ or } V_{IN}=\text{GND}$ | 1.0 | 2.4 | mA |
| | | $V_{CC}=\text{Max.}, 50\% \text{ Duty Cycle, Outputs Open, Four Bits Toggling at } f_1=2.5 \text{ MHz, } \overline{OE}=\text{GND, } V_{IN}\leq 0.2V \text{ or } V_{IN}\geq V_{CC}-0.2V$ | 0.7 | 1.4 ^[11] | mA |
| | | $V_{CC}=\text{Max.}, 50\% \text{ Duty Cycle, Outputs Open, Four Bits Toggling at } f_1=2.5 \text{ MHz, } \overline{OE}=\text{GND, } V_{IN}=3.4V \text{ or } V_{IN}=\text{GND}$ | 1.7 | 5.4 ^[11] | mA |

Notes:

8. Per TTL driven input ($V_{IN}=3.4V$); all other inputs at V_{CC} or GND.
 9. This parameter is not directly testable, but is derived for use in Total Power Supply calculations.
 10. $I_C = I_{QUIESCENT} + I_{INPUTS} + I_{DYNAMIC}$
 $I_C = I_{CC} + \Delta I_{CC} D_H N_t + I_{CCD}(f_0/2 + f_1 N_1)$
 I_{CC} = Quiescent Current with CMOS input levels
 ΔI_{CC} = Power Supply Current for a TTL HIGH input ($V_{IN}=3.4V$)
 D_H = Duty Cycle for TTL inputs HIGH
 N_t = Number of TTL inputs at D_H
 I_{CCD} = Dynamic Current caused by an input transition pair (HLH or LHL)
 f_0 = Clock frequency for registered devices, otherwise zero
 f_1 = Input signal frequency
 N_1 = Number of inputs changing at f_1
- All currents are in millamps and all frequencies are in megahertz.
11. Values for these conditions are examples of the I_{CC} formula. These limits are guaranteed but not tested.

Switching Characteristics Over the Operating Range

| Parameter | Description | FCT157T | | FCT157AT | | | | FCT157CT | | Unit | Fig. No. ^[13] | | |
|--------------------------------------|-----------------------------|----------------------|------|----------------------|------|----------------------|------|----------------------|------|------|--------------------------|--|--|
| | | Commercial | | Military | | Commercial | | Commercial | | | | | |
| | | Min. ^[12] | Max. | | | | |
| t _{PLH} t _{PHL} | Propagation Delay I to Y | 1.5 | 6.0 | 1.5 | 5.8 | 1.5 | 5.0 | 1.5 | 4.3 | ns | 1, 3 | | |
| t _{PLH} t _{PHL} | Propagation Delay E to Y | 1.5 | 10.5 | 1.5 | 7.4 | 1.5 | 6.0 | 1.5 | 4.8 | ns | 1, 5 | | |
| t _{PLH} t _{PHL} | Propagation Delay S to Y | 1.5 | 10.5 | 1.5 | 8.1 | 1.5 | 7.0 | 1.5 | 5.2 | ns | 1, 3 | | |

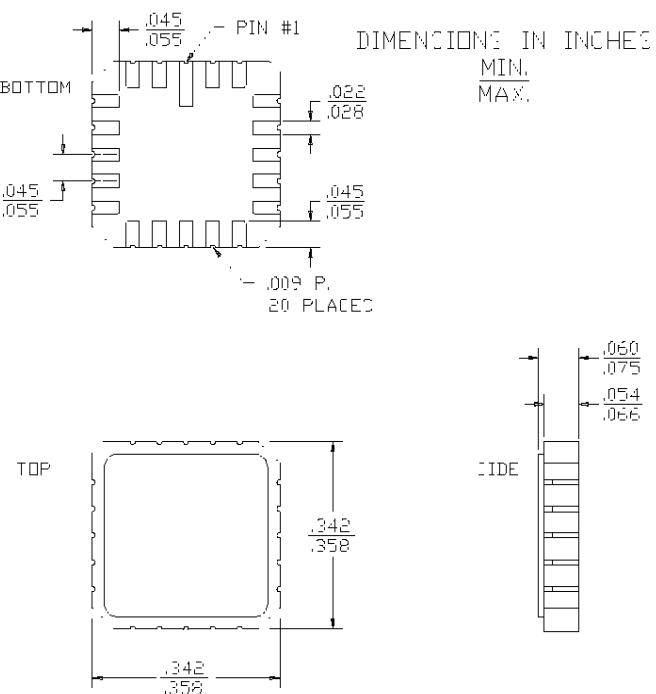
Ordering Information

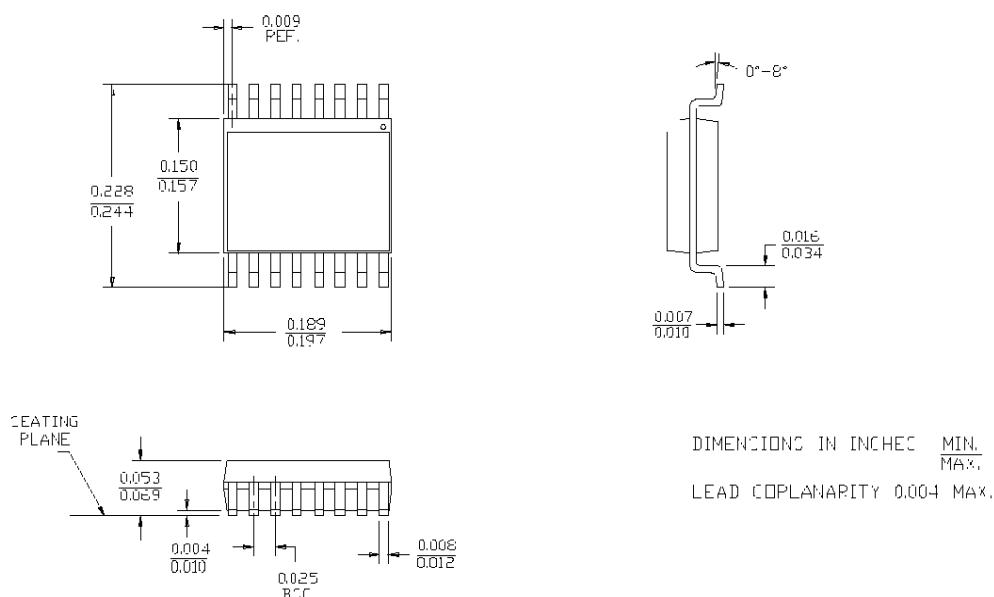
| Speed (ns) | Ordering Code | Package Name | Package Type | Operating Range |
|---------------|-----------------|-----------------|-------------------------------------|--------------------|
| 4.3 | CY74FCT157CTQC | Q1 | 16-Lead (150-Mil) QSOP | Commercial |
| | CY74FCT157CTSOC | S1 | 16-Lead (300-Mil) Molded SOIC | |
| 5.0 | CY74FCT157ATQC | Q1 | 16-Lead (150-Mil) QSOP | Commercial |
| | CY74FCT157ATSOC | S1 | 16-Lead (300-Mil) Molded SOIC | |
| 5.8 | CY54FCT157ATLMB | L61 | 20-Pin Square Leadless Chip Carrier | Military |

Note:

12. Minimum limits are guaranteed but not tested on Propagation Delays.
 13. See "Parameter Measurement Information" in the General Information Section

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Package Diagrams
20-Pin Square Leadless Chip Carrier L61
 MIL-STD-1835 C-2A


Package Diagrams (continued)
16-Lead Quarter Size Outline Q1

16-Lead Molded SOIC S1
